

PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	MMS/15/9469	
1.3 Title of PCI	IMPROVED PACKING for all EEPROM in WLCSP	
1.4 Product Category	All EEPROM in WLCSP	
1.5 Issue date	2015-10-28	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Benoit RODRIGUES
2.1.2 Marketing Manager	Hubert LEDUC
2.1.3 Quality Manager	Rita PAVANO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New Indirect material part number (same supplier or different supplier): Boxes, trays, carriers, back grinding tape, wafer mounting tape, mold tape, ...	STATSChipPAC subcontractor

4. Description of change

	Old	New
4.1 Description	No bubble sheet, no MBB, no desiccant, no humidity indicator, no EPE foam	Adding bubble wrap sheets, Moisture barrier bag, desiccant and humidity indicator, EPE protector foam
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	Impact on form by adding the material of the improved packing	

5. Reason / motivation for change

5.1 Motivation	Will improve resistance to mechanical and environmental stresses during transportation
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	N/A
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7. Timing / schedule

7.1 Date of qualification results	2015-10-22
7.2 Intended start of delivery	2015-10-26
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)9469PpPrdtLst.pdf
PCI NEW PACKING all WLCSP.pdf**10. Affected parts**

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	M24128-DFCS6TP/K	
	M24128S-FCU6T/T	
	M24256-DFCS6TP/K	
	M24512-DFCS6TP/K	
	M24C16-DFCU6TP/K	
	M24C32S-FCU6T/T	
	M24C64-DFCT6TP/K	
	M24C64-FCS6TP/K	
	M24C64S-FCU6T/T	
	M24M01-DFCS6TP/K	
	M24M02-DRCS6TP/K	
	M95128-DFCS6TP/K	
	M95256-DFCS6TP/K	
	M95512-DFCS6TP/K	
	M95640-DFCT6TP/K	
	M95M01-DFCS6TP/K	
	M95M02-DRCS6TP/K	

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Public Products List

PCI Title : IMPROVED PACKING for all EEPROM in WLCSP

PCI Reference : MMS/15/9469

PCI Created on : 22-Oct-2015

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

M24128S-FCU6T/T	M24C64-DFCT6TP/K	M95128-DFCS6TP/K
M24M02-DRCS6TP/K	M24128-DFCS6TP/K	M24M01-DFCS6TP/K
M95M01-DFCS6TP/K	M24512-DFCS6TP/K	M95256-DFCS6TP/K
M24C64-FCS6TP/K	M95M02-DRCS6TP/K	M95512-DFCS6TP/K
M95640-DFCT6TP/K	M24128S-FCU6T/TF	M24C32S-FCU6T/T
M24256-DFCS6TP/K	M24C16-DFCU6TP/K	M24C64S-FCU6T/TF
M24C64S-FCU6T/T		



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IMPROVED PACKING for all EEPROM in WLCSP

What is the change?

The packing of the **EEPROM** in **WLCSP** has been improved by adding:

- EPE protector foam (Fig. 1)
- Moisture barrier bag (MBB) with desiccant and humidity indicator (Fig. 2)
- Two bubble wrap sheets (Fig. 3)



EPE protector foam

Fig. 1



Reel in MBB (no vacuum sealing)

Fig. 2



Bubble wrap sheets

Fig. 3

Why?

The new packing will improve resistance to mechanical and environmental stresses during transportation.

When?

The production of the WLCSP with the improved packing will start from end of October.

How will the change be qualified?

The improved packing has been qualified using the standard ST Microelectronics Corporate Procedures for Quality & Reliability.

What is the impact of the change?

- **Form:** Added bubble wrap sheets, Moisture barrier bag, desiccant, humidity indicator, EPE protector foam
- **Fit:** N/A
- **Function:** N/A

How can the change be seen?

At customer unpacking step.

Appendix A- Product Change Information

Product family / Commercial products:	All EEPROM in WLCSP
Customer(s):	All
Type of change:	Packing
Reason for the change:	Will improve resistance to mechanical and environmental stresses during transportation
Description of the change:	Adding EPE protector foam, 2 bubble wrap sheets and a moisture barrier bag with desiccant and humidity indicator.
Notification to customer:	Week 44 / 2015
Estimated date of first shipment:	Week 44 / 2015 (start of deployment)

Appendix B- Concerned products

M24128-BFCS6TP/A
M24128-DFCS6TP/K
M24128S-FCU6T/T
M24128S-FCU6T/TF
M24C16-DFCU6TP/K
M24C32S-FCU6T/T
M24C64-DFCT6TP/K
M24C64-FCS6TP/K
M24C64S-FCU6T/T
M24C64S-FCU6T/TF
M24M01-DFCS6TP/K
M24M01-RCS6TP/A
M24M02-DRCS6TP/K
M95128-DFCS6TP/K
M95640-DFCT6TP/K
M95M01-DFCS6TP/K
M95M01-RCS6TP/A
M95M02-DRCS6TP/K
M24256-BRCS6TP/A
M24256-DFCS6TP/K
M24512-DFCS6TP/K
M24C08-FCS5TP/S
M24C08-FCT5TP/S
M24C16-FCS5TP/S
M95160-RCS6TP/S
M95256-DFCS6TP/K
M95256-RCS6TP/A
M95512-DFCS6TP/K

